Vishay Siliconix

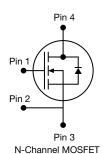
RoHS

HALOGEN FREE

E Series Power MOSFET

PRODUCT SUMMARY					
V _{DS} (V) at T _J max.	700)			
R _{DS(on)} typ. (Ω) at 25 °C	V _{GS} = 10 V	0.316			
Q _g max. (nC)	68				
Q _{gs} (nC)	9				
Q _{gd} (nC)	15				
Configuration	Sing	le			





FEATURES

- Low figure-of-merit (FOM) Ron x Qa
- Low input capacitance (Ciss)
- · Reduced switching and conduction losses
- Ultra low gate charge (Q_a)
- Avalanche energy rated (UIS)
- Kelvin connection for reduced gate noise
- Material categorization: for definitions of compliance please see <u>www.vishav.com/doc?99912</u>

APPLICATIONS

- Server and telecom power supplies
- Switch mode power supplies (SMPS)
- Power factor correction power supplies (PFC)
- Lighting
 - High-intensity discharge (HID)
 - Fluorescent ballast lighting
- Industrial
 - Welding
 - Induction heating
 - Motor drives
 - Battery chargers
 - Renewable energy
 - Solar (PV inverters)

ORDERING INFORMATION	
Package	PowerPAK 8 x 8
Lead (Pb)-free and Halogen-free	SiHH11N65E-T1-GE3

PARAMETER			SYMBOL	LIMIT	UNIT
Drain-Source Voltage			V_{DS}	650	V
Gate-Source Voltage			V_{GS}	± 30	v
Continuous Dunin Comment (T., 150 %C)	V _{GS} at 10 V	T _C = 25 °C T _C = 100 °C	- I _D	12	
Continuous Drain Current (T _J = 150 °C)	V _{GS} at 10 V	T _C = 100 °C		8	Α
Pulsed Drain Current ^a			I _{DM}	27	
Linear Derating Factor				1	W/°C
Single Pulse Avalanche Energy b			E _{AS}	127	mJ
Maximum Power Dissipation			P _D	130	W
Operating Junction and Storage Temperature Range			T _J , T _{stg}	-55 to +150	°C
Drain-Source Voltage Slope T _J = 125 °C			4).//d+	70	1//20
Reverse Diode dV/dt ^c			dV/dt	24	V/ns

Notes

- a. Repetitive rating; pulse width limited by maximum junction temperature.
- b. V_{DD} = 140 V, starting T_J = 25 °C, L = 28.2 mH, R_q = 25 Ω , I_{AS} = 3 A.
- c. $I_{SD} \le I_D$, $dI/dt = 100 \text{ A/}\mu\text{s}$, starting $T_J = 25 \,^{\circ}\text{C}$.



Vishay Siliconix

THERMAL RESISTANCE RATINGS				
PARAMETER	SYMBOL	TYP.	MAX.	UNIT
Maximum Junction-to-Ambient	R _{thJA}	42	55	°C/W
Maximum Junction-to-Case (Drain)	R _{thJC}	0.72	0.96	C/VV

PARAMETER	SYMBOL	TES	T CONDITIONS	MIN.	TYP.	MAX.	UNIT
Static						l	
Drain-Source Breakdown Voltage	V _{DS}	V _{GS} =	= 0 V, I _D = 250 μA	650	-	-	V
V _{DS} Temperature Coefficient	$\Delta V_{DS}/T_{J}$	Referenc	e to 25 °C, I _D = 1 mA	-	0.77	-	V/°C
Gate-Source Threshold Voltage (N)	V _{GS(th)}	V _{DS} =	V _{GS} , I _D = 250 μA	2	-	4	V
Oala Oa aaalaalaa		V _{GS} = ± 20 V		-	-	± 100	nA
Gate-Source Leakage	I _{GSS}	1	$V_{GS} = \pm 30 \text{ V}$	-	-	± 1	μΑ
Zana Oata Valta na Duain Oannant		V _{DS} =	650 V, V _{GS} = 0 V	-	-	1	
Zero Gate Voltage Drain Current	I _{DSS}	V _{DS} = 520 V	, V _{GS} = 0 V, T _J = 125 °C	-	-	50	μA
Drain-Source On-State Resistance	R _{DS(on)}	V _{GS} = 10 V	I _D = 6 A	-	0.316	0.363	Ω
Forward Transconductance	9 _{fs}	V _{DS}	= 30 V, I _D = 6 A	-	4.1	-	S
Dynamic							
Input Capacitance	C _{iss}	$V_{GS} = 0 V$		-	1257	-	
Output Capacitance	C _{oss}	١ ,	V _{DS} = 100 V,	-	60	-	
Reverse Transfer Capacitance	C _{rss}		f = 1 MHz	-	4	-	
Effective Output Capacitance, Energy Related ^a	C _{o(er)}	٧, ٥١	/+- 500 V V 0 V	-	43	-	pF
Effective Output Capacitance, Time Related ^b	C _{o(tr)}	V _{DS} = 0 \	/ to 520 V, V _{GS} = 0 V	-	168	-	
Total Gate Charge	Qg			-	34	68	
Gate-Source Charge	Q _{gs}	V _{GS} = 10 V	$I_D = 6 A, V_{DS} = 520 V$	-	9	-	nC
Gate-Drain Charge	Q _{gd}			-	15	-	
Turn-On Delay Time	t _{d(on)}			-	19	38	
Rise Time	t _r	V _{DD} =	= 520 V, I _D = 6 A,	-	28	56	1
Turn-Off Delay Time	t _{d(off)}		$= 10 \text{ V}, \text{ R}_{\text{g}} = 9.1 \Omega$	-	39	78	ns
Fall Time	t _f	7		-	23	46	
Gate Input Resistance	R _g	f = 1	MHz, open drain	0.3	0.7	1.4	Ω
Drain-Source Body Diode Characteristic	s						
Continuous Source-Drain Diode Current	I _S	MOSFET sym showing the	MOSFET symbol showing the		-	12	^
Pulsed Diode Forward Current	I _{SM}	integral revers p - n junction	Ç. 7	-	-	27	A
Diode Forward Voltage	V_{SD}	T _J = 25 °C, I _S = 6 A, V _{GS} = 0 V		-	0.9	1.2	V
Reverse Recovery Time	t _{rr}	_		-	321	642	ns
Reverse Recovery Charge	Q_{rr}		5 °C, I _F = I _S = 6 A, 100 A/µs, V _B = 25 V	-	3.8	7.6	μC
Reverse Recovery Current	I _{RRM}		100 Ανμο, νΗ = 20 ν	-	19	-	Α

Notes

- a. $C_{oss(er)}$ is a fixed capacitance that gives the same energy as C_{oss} while V_{DS} is rising from 0 % to 80 % V_{DS} .
- b. $C_{oss(tr)}$ is a fixed capacitance that gives the same charging time as C_{oss} while V_{DS} is rising from 0 % to 80 % V_{DS} .



TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)

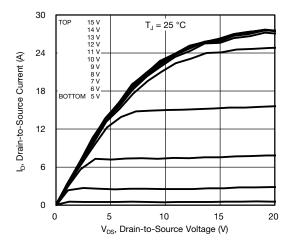


Fig. 1 - Typical Output Characteristics

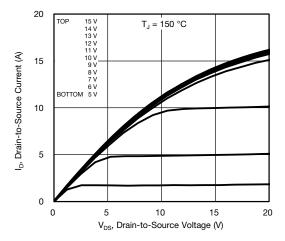


Fig. 2 - Typical Output Characteristics

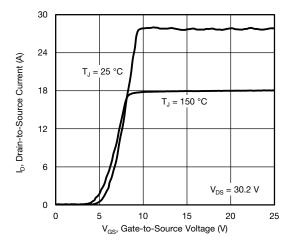


Fig. 3 - Typical Transfer Characteristics

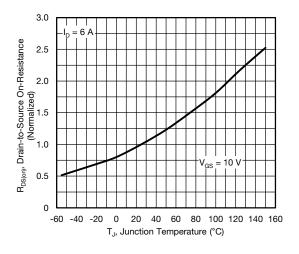


Fig. 4 - Normalized On-Resistance vs. Temperature

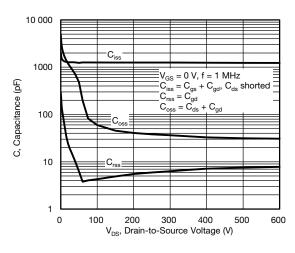


Fig. 5 - Typical Capacitance vs. Drain-to-Source Voltage

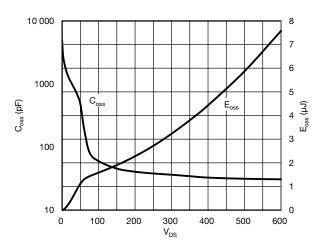


Fig. 6 - C_{OSS} and E_{OSS} vs. V_{DS}



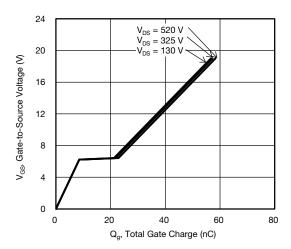


Fig. 7 - Typical Gate Charge vs. Gate-to-Source Voltage

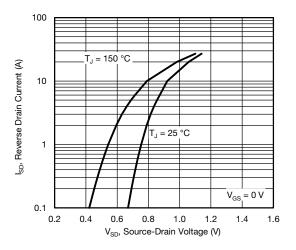


Fig. 8 - Typical Source-Drain Diode Forward Voltage

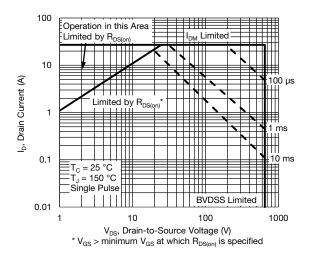


Fig. 9 - Maximum Safe Operating Area

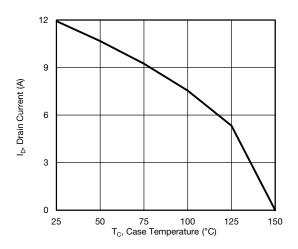


Fig. 10 - Maximum Drain Current vs. Case Temperature

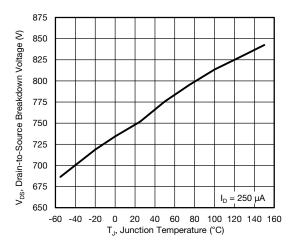


Fig. 11 - Temperature vs. Drain-to-Source Voltage



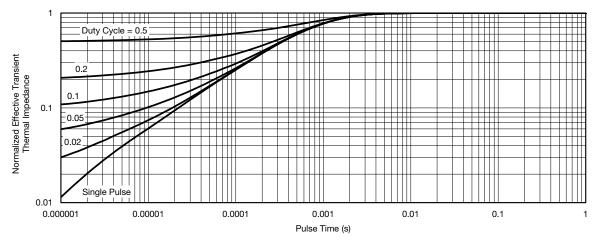


Fig. 12 - Normalized Thermal Transient Impedance, Junction-to-Case

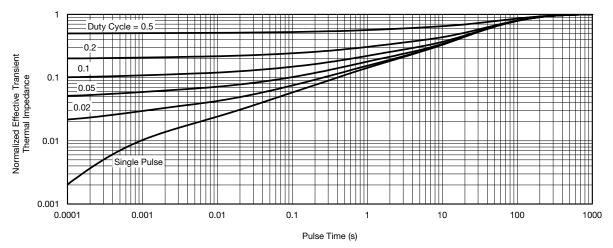


Fig. 13 - Normalized Thermal Transient Impedance, Junction-to-Ambient

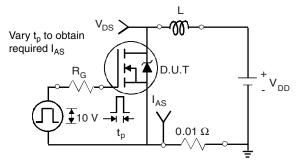


Fig. 14 - Switching Time Test Circuit

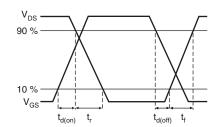


Fig. 15 - Switching Time Waveforms

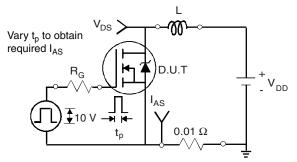


Fig. 16 - Unclamped Inductive Test Circuit

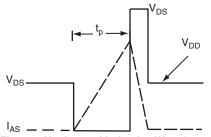


Fig. 17 - Unclamped Inductive Waveforms



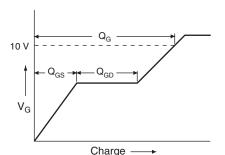


Fig. 18 - Basic Gate Charge Waveform

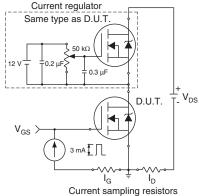
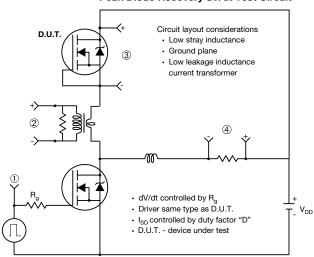


Fig. 19 - Gate Charge Test Circuit

Peak Diode Recovery dV/dt Test Circuit



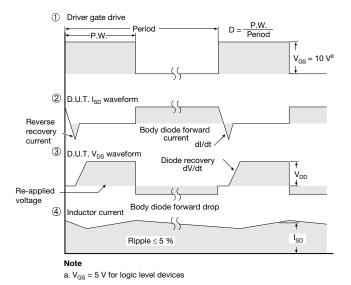


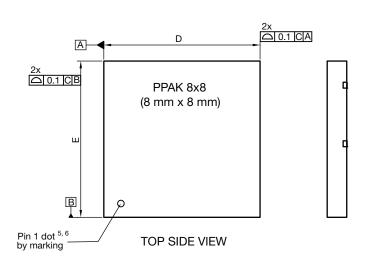
Fig. 20 - For N-Channel

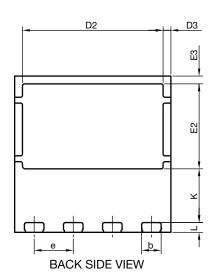
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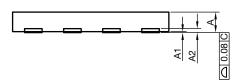




PowerPAK® 8 x 8 Case Outline







DIM	MILLIMETERS			INCHES			
DIM.	MIN.	NOM.	MAX.	MIN.	NOM.	MAX.	
A 8	0.95	1.00	1.05	0.037	0.039	0.041	
A1	0.00	-	0.05	0.000	-	0.002	
A2	020 ref.			0.008 ref.			
b ⁴	0.95	1.00	1.05	0.037	0.039	0.041	
D	7.90	8.00	8.10	0.311	0.315	0.319	
D2	7.10	7.20	7.30	0.280	0.283	0.287	
D3	0.40 BSC			0.016 BSC			
е	2.00 BSC		0.079 BSC				
Е	7.90	8.00	8.10	0.311	0.315	0.319	
E2	4.30	4.35	4.40	0.169	0.171	0.173	
E3	0.40 BSC			0.016 BSC			
K	2.75 BSC		0.108 BSC				
L	0.45	0.50	0.55	0.018	0.020	0.022	
N ³	8			8 8			

Notes

- 1. Use millimeters as the primary measurement.
- 2. Dimensioning and tolerances conform to ASME Y14.5 M 1994.
- 3. N is the number of terminals.
- 4. Package warpage max. 0.08 mm.
- 5. The pin 1 identifier must be existed on the top surface of the package by using indentation mark or other feature of package body.
- 6. Exact shape and size of this feature is optional.

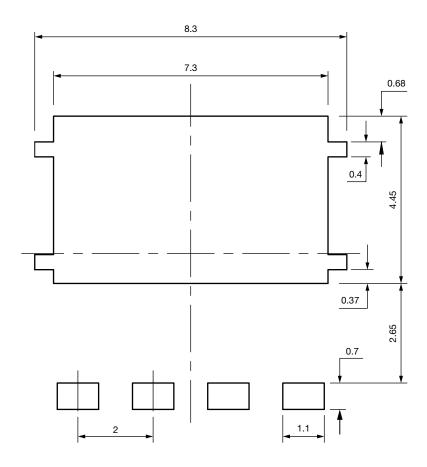
ECN: T15-0225-Rev. A, 18-May-15

DWG: 6041

Revision: 18-May-15 1 Document Number: 67859



Recommended Minimum PADs for PowerPAK® 8 mm x 8 mm



Dimensions in millimeters



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Revision: 02-Oct-12 Document Number: 91000

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